



- NOTES:
- MATERIAL:
HOUSING:LCP, BLACK, UL 94V-0
CONTACT:PHOSPHORBRONZE, T=0.10MM
SHELL:STAINLESS STEEL T=0.15MM
 - FINISH
CONTACT: 50U' MIN PLATING OVER ALL
GOLD FLASH ON THE CONTACT AREA AND
SOLDER AREA
SHELL:SELECTIVE GOLD FLASH IN SOLDER TAIL AREA
50U' NI MIN. PLATING OVER ALL
 - ALL DIMENSIONS MARKED ▼ MUST BE CONTROLLED BY QC
 - RATED PARAMETERS OF CONNECTOR
4-1.Operating temperature: -40°C to 70°C
4-2. Rated Current: 0.5A
4-3. Rated Voltage: 30V DC Per Contact
 - ELECTRICAL MECHANICAL ENVIRONMENTAL
5-1. Dielectric withstanding Voltage : 500V AC 1min.
5-2. Insulation Resistance: 1000 MΩMin.
5-3. Normal Force: 100g Min. Per Pin
5-4. Durability: 1000 cycles
5-5. Heat Resistance: 20mΩ MAX.

SIM CARD PIN NO.	PIN NO.
SIM CARD P1	VCC
SIM CARD P2	RST
SIM CARD P3	CLK
SIM CARD P4	RESERVED
SIM CARD P5	GND
SIM CARD P6	VPP
SIM CARD P7	I/O
SIM CARD P8	RESERVED

				UNITS: mm	GENERAL TOLERANCE		DRAW:	PART NO: S34-0B08F15C
				DATE: 11/06/2015	X. ±0.25	X' ±5.00'	CHECKED:	TITLE: MICRO SIM CARD成品H=1.50mm
				SCALE: 8/1	.X ±0.15	.X' ±3.00'	APPROVE:	DRAWING NO:
				SHEET: 1/1	.XX ±0.10	.XX' ±1.00'		
				REV. A	.XXX ±0.05			
REV.	ECN NO.	DESCRIPTION	DATE		MATERIAL:		昆山捷皇电子精密科技有限公司 HONGRIDA ELECTRONIC TECHNOLOGY CO., LTD.	
		NEW	11/06/2015		FINISH: SEE NOTE			